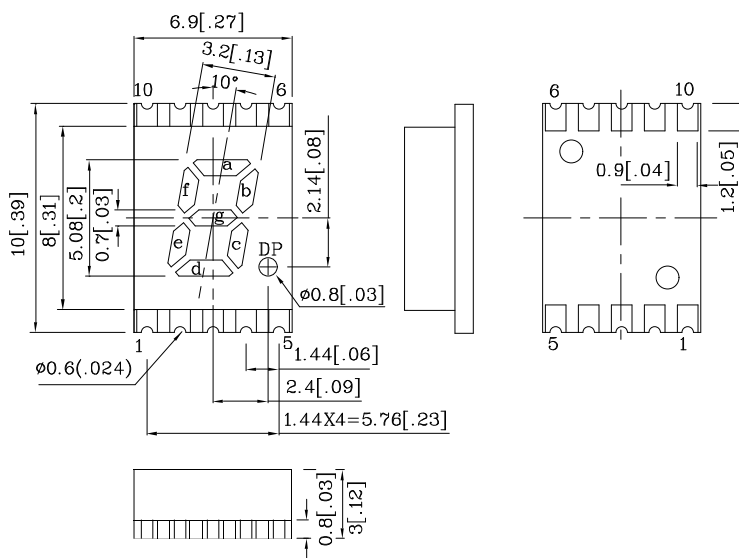
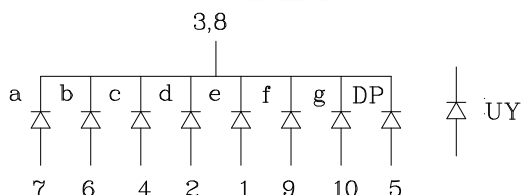


- 0.21 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE : 650 PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

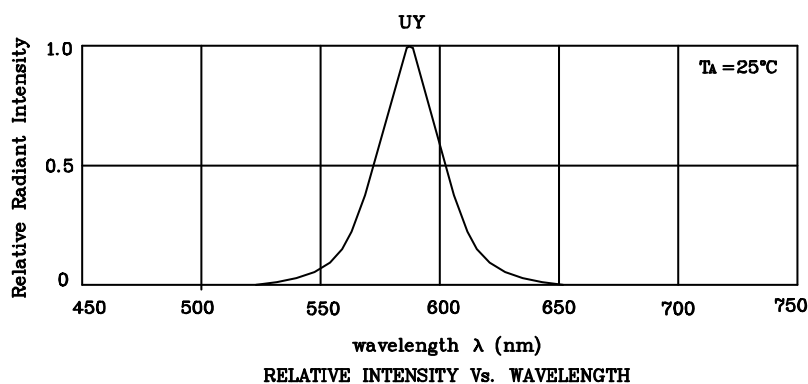


1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3.The gap between the reflector and PCB shall not exceed 0.25mm.
- 4.Specifications are subject to change without notice.

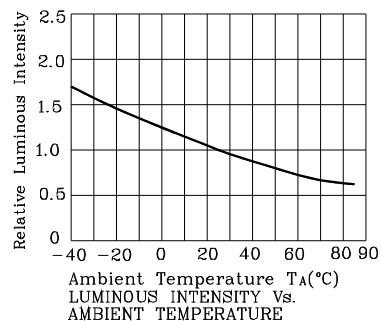
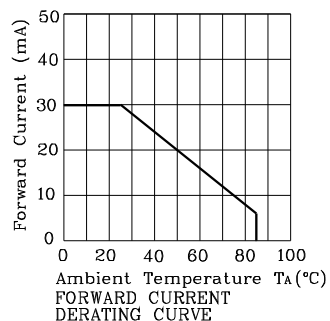
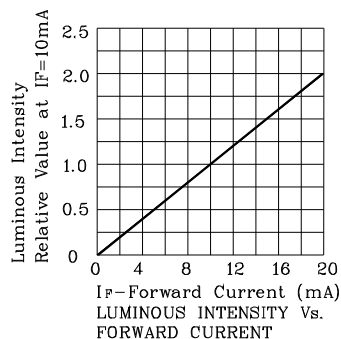
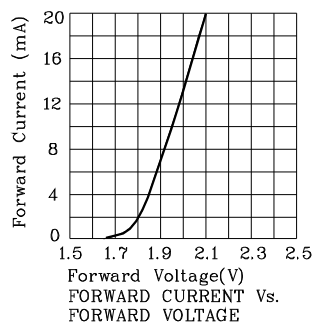
Absolute Maximum Ratings (TA=25°C)		UY (GaAsP/ GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (T _A =25°C)		UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.95	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emis- sion (Typ.) (I _F =10mA)	λ P	590	nm
Wavelength of Dominant Emission (Typ.) (I _F =10mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm λ P	Description	
			min.	typ.		
ZFUY05C	Yellow	GaAsP/GaP	480	1890	590	Common Cathode. Rt. Hand Decimal
Published Date : FEB 28. 2008		Drawing No : SDSA5287		V2	Checked : Shin Chi	P.1/4



❖ **UY**



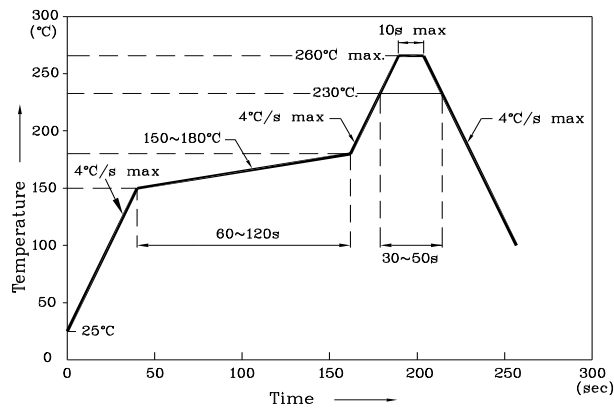
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

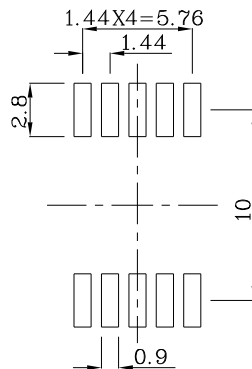
Reflow Soldering Profile For Lead-free SMT Process.



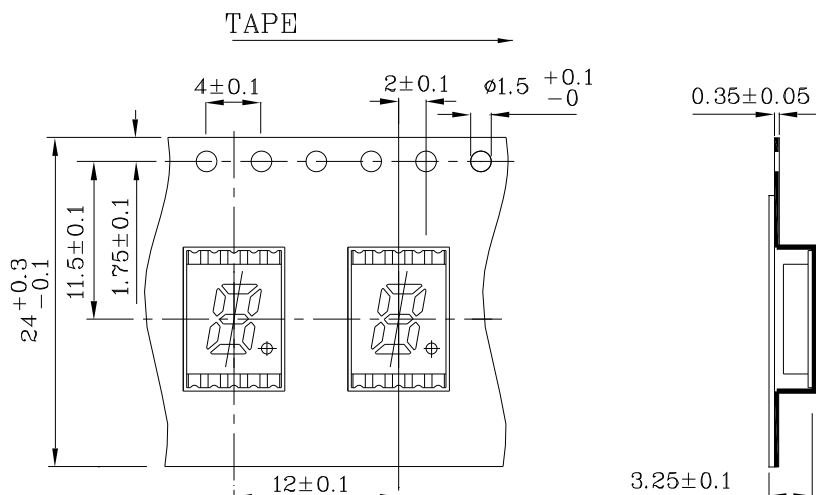
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance: ± 0.15)

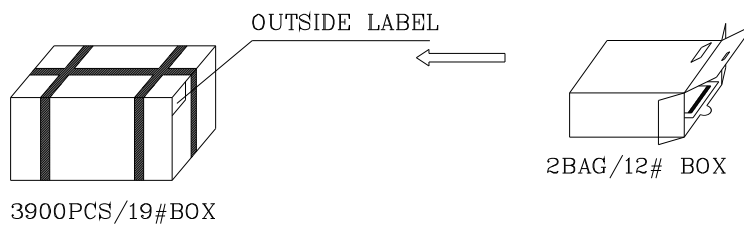
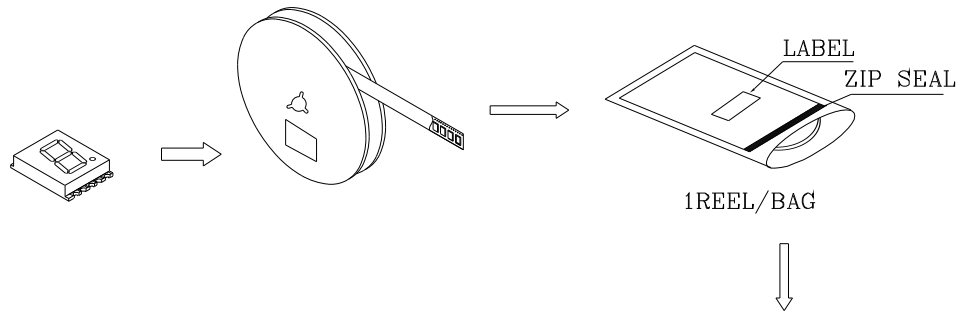


❖ Tape Specification (Units : mm)

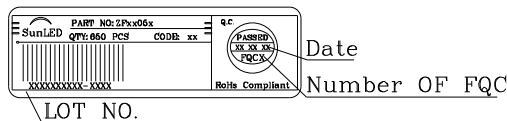


PACKING & LABEL SPECIFICATIONS

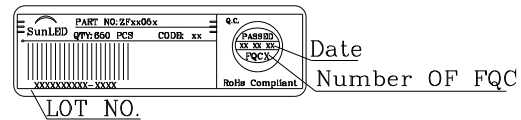
ZFUY05C



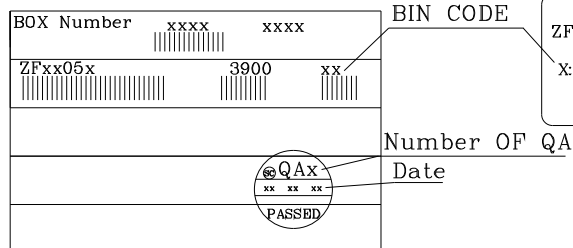
Inside LABEL Paste On The TAPE



Outside LABEL Paste On The BAG



Outside LABEL Paste On The 19#Box



Outside LABEL Paste On The 12#Box

